

# FH30120D

## N-Channel Trench Power MOSFET

### Features

- 30V,120A
- $R_{DS(ON)}=2.9m\Omega$  (Typ.) @  $V_{GS}=10V$
- $R_{DS(ON)}=4.3m\Omega$  (Typ.) @  $V_{GS}=4.5V$
- Advanced Trench Technology
- Provide Excellent  $R_{DS(ON)}$  and Low Gate Charge

### Application

- Load Switch
- PWM Application
- Power management



### Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Max.	Units
$V_{DSS}$	Drain-Source Voltage	30	V
$V_{GSS}$	Gate-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_C = 25^\circ\text{C}$	120
		$T_C = 100^\circ\text{C}$	68
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	400	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>	180	mJ
$P_D$	Power Dissipation	95	W
$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.7	$^\circ\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +175	$^\circ\text{C}$

**Electrical Characteristics** ( $T_C=25^\circ\text{C}$  unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
<b>Off Characteristic</b>						
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS}=30V, V_{GS}=0V,$	-	-	1.0	$\mu A$
$I_{GSS}$	Gate to Body Leakage Current	$V_{DS}=0V, V_{GS}=\pm 20V$	-	-	$\pm 100$	nA
<b>On Characteristics</b>						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	1.0	1.6	2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note3</small>	$V_{GS}=10V, I_D=30A$	-	2.9	3.8	m $\Omega$
		$V_{GS}=4.5V, I_D=20A$	-	4.3	5.9	
$g_{FS}$	Forward Transconductance	$V_{DS}=10V, I_D=10A$	-	15.5	-	S
<b>Dynamic Characteristics</b>						
$C_{iss}$	Input Capacitance	$V_{DS}=25V, V_{GS}=0V,$ $f=1.0MHz$	-	2200	-	pF
$C_{oss}$	Output Capacitance		-	280	-	pF
$C_{rss}$	Reverse Transfer Capacitance		-	177	-	pF
$Q_g$	Total Gate Charge	$V_{DS}=15V, I_D=24A,$ $V_{GS}=10V$	-	42	-	nC
$Q_{gs}$	Gate-Source Charge		-	4	-	nC
$Q_{gd}$	Gate-Drain("Miller") Charge		-	13	-	nC
<b>Switching Characteristics</b>						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD}=15V,$ $I_D=15A, R_{GEN}=3.3\Omega,$ $V_{GS}=10V$	-	12.6	-	ns
$t_r$	Turn-on Rise Time		-	19.5	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	42.8	-	ns
$t_f$	Turn-off Fall Time		-	13.2	-	ns
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	-	120	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	-	400	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS}=0V, I_S=30A$	-	-	1.2	V
$t_{rr}$	Body Diode Reverse Recovery Time	$I_F=30A, di/dt=100A/\mu s$	-	19	-	ns
$Q_{rr}$	Body Diode Reverse Recovery Charge		-	11	-	nC

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. EAS condition:  $T_J=25^\circ\text{C}, V_{DD}=25V, V_G=10V, R_G=25\Omega$

3. Pulse Test: Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 2\%$

Typical Performance Characteristics

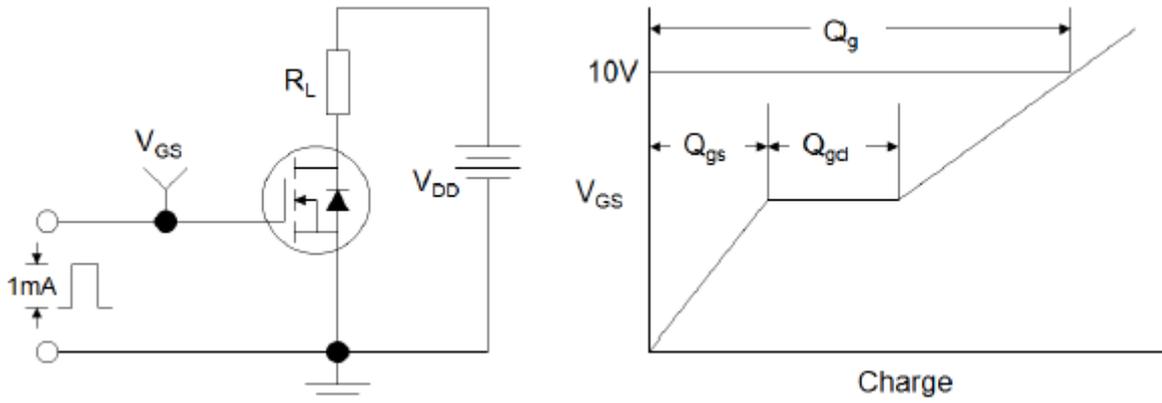


Figure1:Gate Charge Test Circuit & Waveform

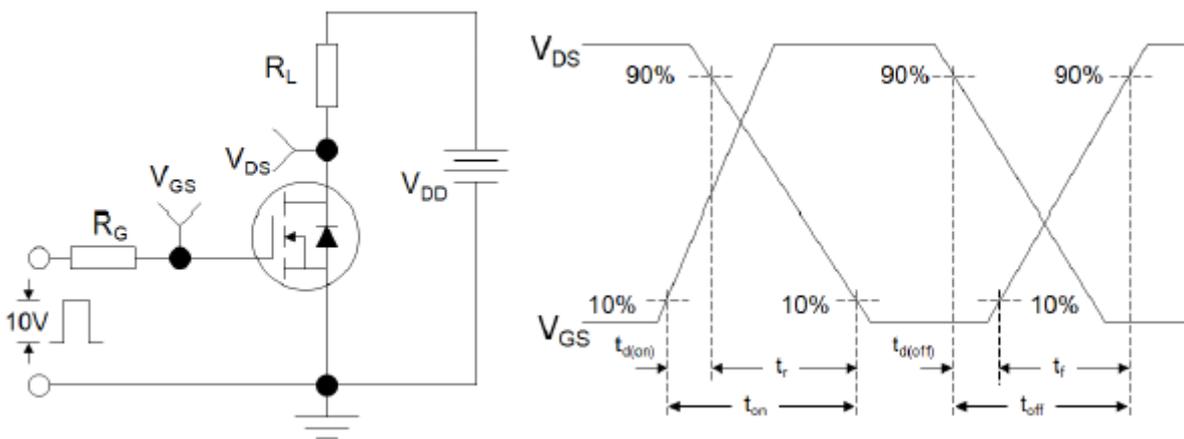


Figure 2: Resistive Switching Test Circuit & Waveforms

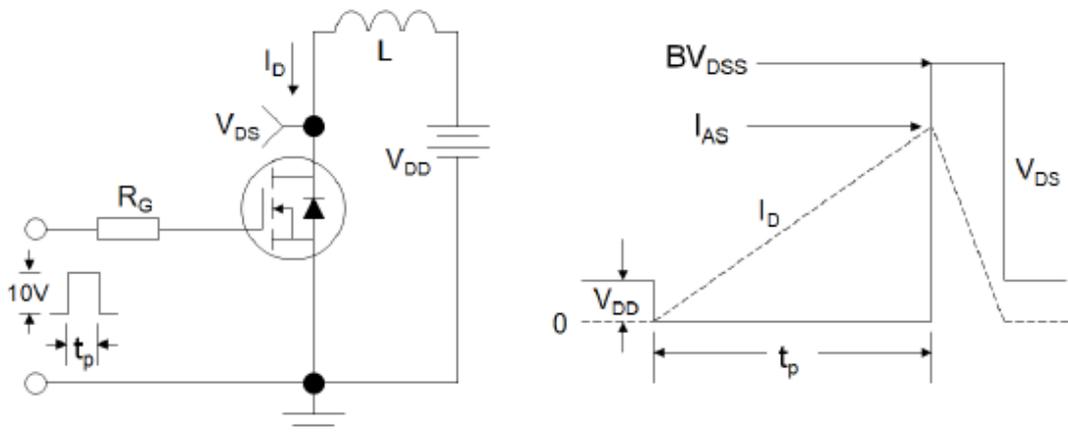


Figure 3:Unclamped Inductive Switching Test Circuit & Waveforms

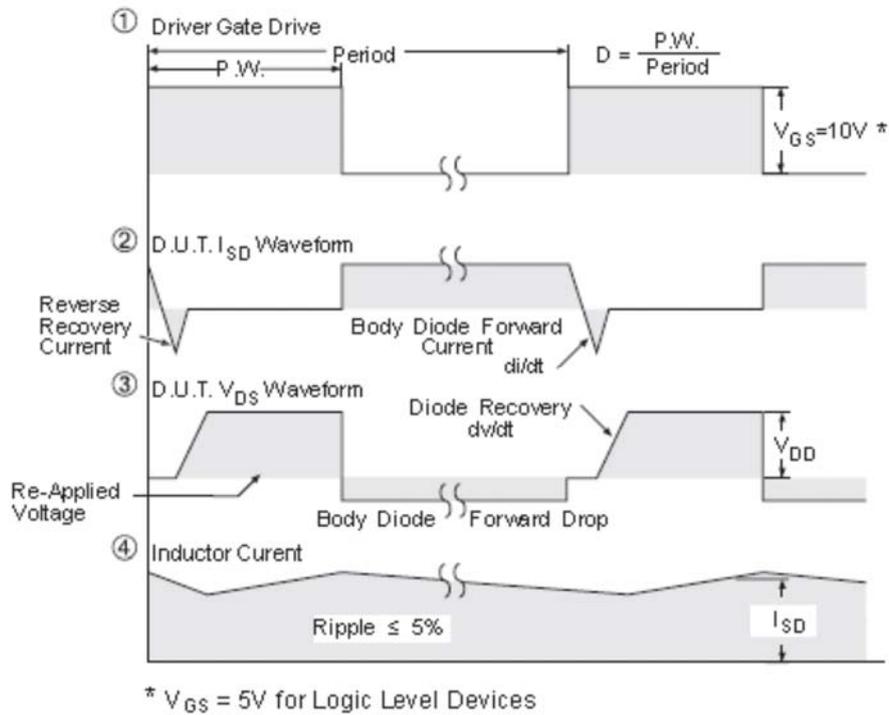
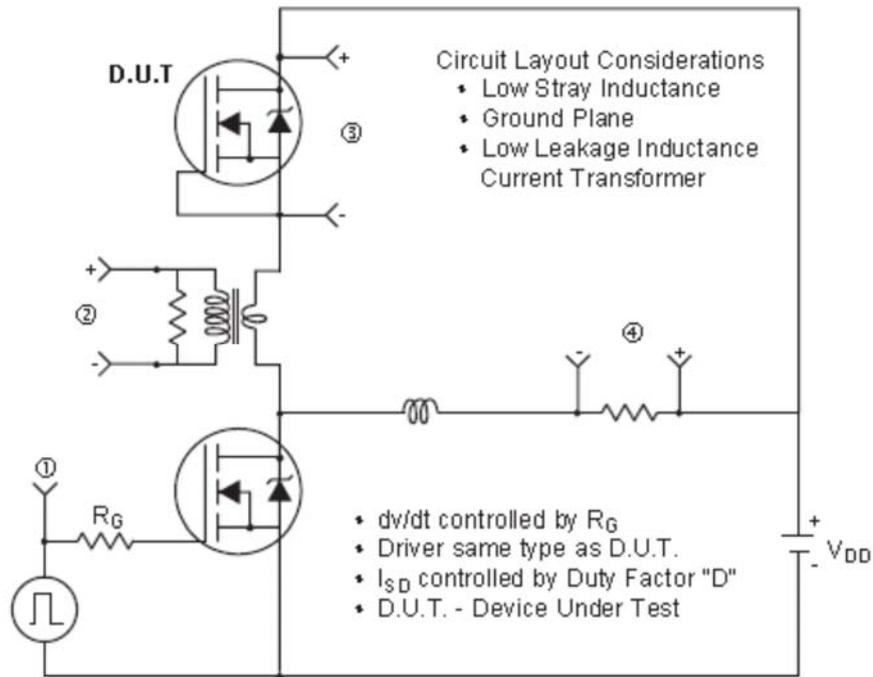
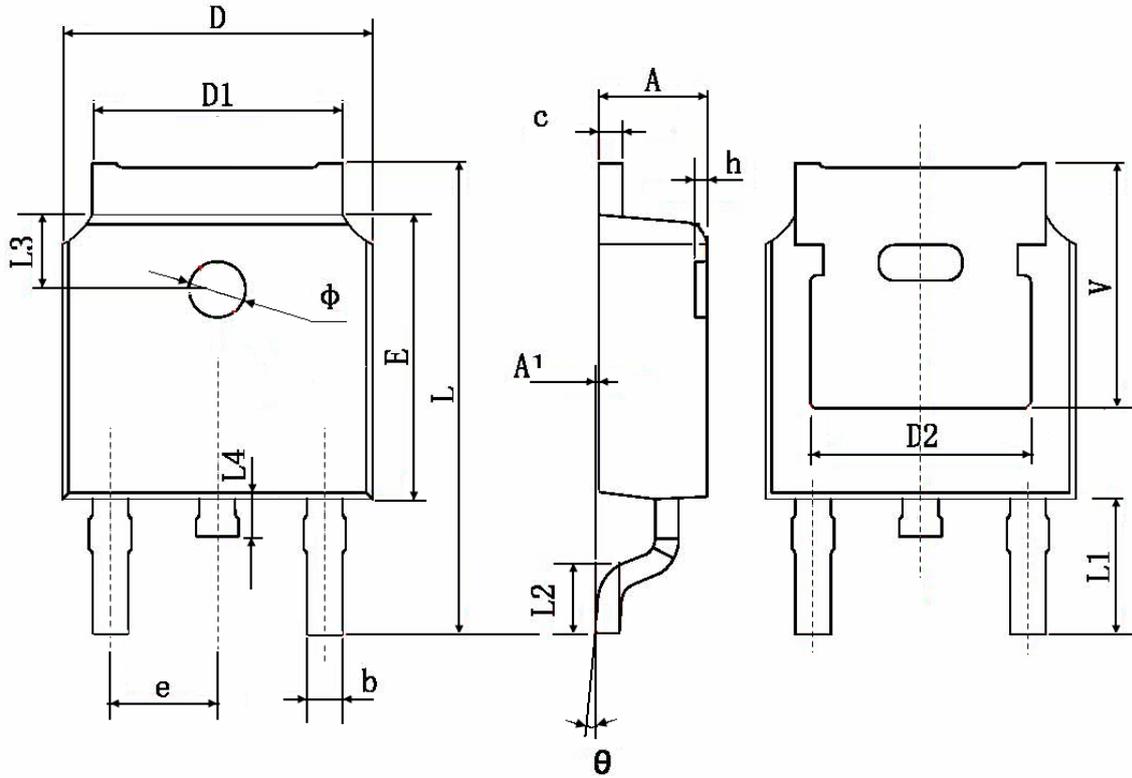


Figure 4: Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms (For N-channel)

Package Information : TO-252



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	